

# **North America Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2), 5D/3D and others), By End User (Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others), By Country, Industry Analysis and Forecast, 2020 - 2026**

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## **Abstracts**

The North America Advanced Packaging Market would witness market growth of 11.6% CAGR during the forecast period (2020-2026).

Manufacturing processes rely on the specifications that consumers will satisfy in order to guarantee the functionality of the finished product. Integrated circuits are designed to have all the electrical functions necessary and to fit into a particular range of packages. The bond pads on the chip are connected by wire bonding to the pins of the conventional package. Design rules for standard packages require bond pads to be located on the perimeter of the chip. In order to prevent two designs for the same chip, a redistribution layer is usually required to connect bumps to bond pads.

The dual in-line package is an electronic component package with a rectangular housing and two parallel rows of electrical connectors. The package may be placed through a hole on a printed circuit board (PCB). More and more complex circuits required more signal and power supply lines. Eventually, microprocessors and related complex devices needed more leads than could be mounted on a DIP box, leading to the development of higher-density chip carriers. In addition, square and rectangular packages also made it easier for the printed-circuit traces to be routed under packages. Semiconductor packaging technology has advanced significantly and several thousand different types of semiconductor packages have been manufactured. Industries such as aerospace, healthcare, data centers and many other sectors are projected to be the main growth factors for the advanced semiconductor packaging industry in the coming

years. In view of market apprehensions, several semiconductor companies around the world have developed different modes of operation to meet the requirements of the industry.

Based on Type, the market is segmented into Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others. Based on End User, the market is segmented into Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others. Based on countries, the market is segmented into U.S., Mexico, Canada, and Rest of North America.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include Qualcomm, Inc., Intel Corporation, IBM Corporation, Texas Instruments, Inc., Analog Devices, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd. (Samsung Group), Amkor Technology, Inc., Brewer Science, Inc., and MICROCHIP Technology, Inc.

## Scope of the Study

## Market Segmentation:

### By Type

Flip-Chip Ball Grid Array

Flip Chip CSP

Wafer Level CSP

2.5D/3D

Others

### By End User

Consumer Electronics

Automotive

Industrial

Aerospace & Defense

Healthcare & Life Sciences

Others

## By Country

US

Canada

Mexico

Rest of North America

## Companies Profiled

Qualcomm, Inc.

Intel Corporation

IBM Corporation

Texas Instruments, Inc.

Analog Devices, Inc.

Renesas Electronics Corporation

Samsung Electronics Co., Ltd. (Samsung Group)

Amkor Technology, Inc.

Brewer Science, Inc.

Microchip Technology, Inc.

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